NexSil™ SP–521K
GERMANIUM POLISHING SLURRY

PRODUCT DESCRIPTION
NexSil SP–521K is developmental polishing slurry for Germanium wafer polishing. The product is supplied at pH 9–10 and 30% solids.

Polishing of Germanium wafers using NexSil SP–521K should be done at 3–4 psi on the wafer surface and at a 25°C temperature. Slurry flow will depend on the pad and process conditions being used. The slurry should be used at the concentration supplied. Typical removal rates are 0.4 to 0.5 microns per minute at 3.7 psi using a Suba™ 1200 pad.

TYPICAL PROPERTIES
Appearance: Translucent Slurry
Solids, %: 30
pH: 9 – 10
Particle Size, nm, by Malvern HPPS: 110 – 135

PACKAGING
NexSil SP–521K polishing slurry is available in 5-gallon pails and 55-gallon drums.

STORAGE
NexSil SP–521K polishing slurry should be stored above 32°F to protect from freezing.

SAFETY
NexSil SP–521K polishing slurry is mildly alkaline and may cause eye and skin irritation. Observe precautions printed on the package label. A Safety Data Sheet will be supplied on request.

FOR ADDITIONAL INFORMATION OR TO ORDER MATERIAL
P.O. Box 349 508–881–2220 Local Area
Megunko Road Fax: 508–881–1855
Ashland, MA 01721 Internet: www.nyacol.com

Information herein is accurate to the best of our knowledge. Suggestions are made without warranty or guarantee of results. Before using, user should determine the suitability of the product for the intended use and user assumes the risk and liability in connection therewith. We do not suggest violation of any existing patents or give permission to practice any patented invention without a license. 20130529

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